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Notice of Allowability	Application No.	Applicant(s)
	10/663,797	TAMAKI ET AL.
	Examiner	Art Unit
	Tuan T Dinh	2841
The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.		
1. This communication is responsive to <u>09/17/03</u> .		
2. The allowed claim(s) is/are <u>1-10</u> .		
3. The drawings filed on <u>17 September 2003</u> are accepted by the Examiner.		
 4.		
 Attachment(s) 1. ☑ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☑ Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date 0917/03. 4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material 	6. ☐ Interview Summary Paper No./Mail Dat 8), 7. ☐ Examiner's Amenda	te

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DETAILED ACTION

Allowable Subject Matter

1. Claims 1-10 are allowed.

The following is an examiner's statement of reasons for allowance: the references cited disclose an electronic apparatus comprising: a function module having a multiplayer wiring unit including first signal and ground wirings, a first signal via, first signal and ground pads; a multiplayer circuit board including second signal and ground wirings, a second signal via, a second ground pad, third signal and ground pads; a first conductor (solder ball) that connects the first and second signal pads and; a central conductor of a coaxial cable is connected the third signal pad, in combination with the other claimed elements. The Prior Art (figure 21) admitted by applicant discloses a sensor module (2001) having signal and ground (2003, 2005) electrically connected to signal and ground pads (2008, 2010) of a coaxial cable (2015). However, the chip and the board, and the internal structure of them is not taught. Kawada et al disclose a module for mounting driver IC;s as shown in figure 29 comprising a circuit board (6). and a connector (5). Kawada does not disclose the details of the signal wiring and potential wiring with the chip or the board or how they are connected to the external connection. Selna discloses a BGA package, see figure 1, comprising a laminate substrate (4) having signal and ground pads (10B, 10C) electrically connected to signal and ground pads (20) of a circuit board (18) by solder balls (14). However, Selna does not teach the internal wiring of the board, the specific connections, and the coaxial

cable. Further, there is no suggestion to combine these references, and combining them would still not yield the internal wiring details of the circuit board, and their connection to the chip and the coaxial cable as claimed.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

2. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Kresge et al., Selna, Hsu, and Kawada et al. disclose related art.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kammie Cuneo can be reached on 571-272-1957. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Tuan Dinh December 09, 2004.

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